



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE7469G V53			<b>Issued</b>	3. July 2019			
<b>MA#</b>	MA005342984							
<b>Package</b>	PG-DSO-12-11			<b>Weight*</b>	401.98 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.559	0.89	0.89	8853	8853
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		172	
	non noble metal	iron	7439-89-6	0.230	0.06		573	
	non noble metal	copper	7440-50-8	230.106	57.24	57.32	572428	573173
	non noble metal	aluminium	7429-90-5	0.158	0.04	0.04	392	392
wire	non noble metal	aluminium	7429-90-5	0.158	0.04	0.04	392	392
encapsulation	organic material	carbon black	1333-86-4	0.316	0.08		787	
	plastics	epoxy resin	-	14.548	3.62		36191	
	inorganic material	silicondioxide	60676-86-0	143.270	35.64	39.34	356407	393385
leadfinish	non noble metal	tin	7440-31-5	4.235	1.05	1.05	10536	10536
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		3	
	non noble metal	nickel	7440-02-0	0.537	0.13	0.13	1336	1339
solder	non noble metal	tin	7440-31-5	0.099	0.02		246	
	noble metal	silver	7440-22-4	0.124	0.03		308	
	non noble metal	lead	7439-92-1	4.731	1.18	1.23	11768	12322
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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